

Final Product Change Notification

Issue Date: 22-Jan-2020 Effective Date: 22-Feb-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



201909026F01

Management Summary

SOT886 assembly and test will be transferred from ATGD and ATSN to ATBK. This streamlines manufacturing flow and improves package reliability with introduction of roughened leadframe and Cu wire.

Change Category

[] Wafer Fab Process	[X] Assembly Process	[] Product Marking	[X] Test Location	[] Design
[] Wafer Fab Materials	[X] Assembly	[] Mechanical Specification	[]Test Process	[] Errata
[] Wafer Fab Location	Materials [X] Assembly	[X] Packing/Shipping/Labeling	[X] Test Equipment	•
[] Firmware	Location [] Other			coverage

XSON6 (SOT886)
Assembly/Test Transfer from ATGD and ATSN to ATBK - Final Notice

Description of Change

NXP Semiconductors is transferring assembly and test of the SOT886 (XSON6) package from ATSN and ATGD to ATBK. Standard ATBK BOM and flows will be used.

Product data sheets are updated and available on the NXP website indicating the new orderable part numbers reflecting the use of Static Shielding Bags (SSB).

Reason for Change

Move production to an NXP facility to assure product quality and delivery.

Identification of Affected Products

Packing Labels will show Product Manufacturing Code (PMC) "n" to reflect ATBK assembly.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 27-Jan-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification Issue Date Effective DateTitle

201909026A27-Oct- XSON6 (SOT886) Assembly/Test Transfer from ATGD and

2019 ATSN to ATBK

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 21-Feb-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Numbers

NX3L1T5157GM,132